3.3 V/5 V, 20 Mbit/sec, Logic Gate Optocoupler in Stretched Body SOP 6-Pin

Description

The FOD8173 series packaged in a stretched body 6–pin small outline plastic package, consists of an aluminum gallium arsenide (AlGaAs) light emitting diode and a CMOS detector IC comprises an integrated photodiode, a high speed transimpedance amplifier and a voltage comparator with a totem–pole output driver. The electrical and switching characteristics are guaranteed over the extended industrial temperature range of -40° C to 100° C and a V_{DD} range of 3 V to 5.5 V.

Features

- FOD8173T 8 mm Creepage and Clearance Distance, and 0.4 mm insulation distance to achieve reliable and high voltage insulation
- High Noise Immunity characterized by common mode transient immunity (CMTI)
- 20 kV/µs Minimum CMTI
- 3.3 V and 5 V CMOS Compatibility
- Specifications Guaranteed Over 3 V to 5.5 V supply voltage and -40 to 100°C extended industrial temperature range
- High Speed
 - 20 Mbit/sec Date Rate (NRZ)
 - 55 ns max. Propagation Delay
 - 20 ns max. Pulse Width Distortion
- Safety and regulatory pending approvals
 - UL1577, 5,000 VAC_{RMS} for 1 min.
 - DIN-EN/IEC60747-5-5, 1,140 V peak working insulation voltage for FOD8173T

Typical Applications

- Microprocessor System Interface
 SPI, I2C
- Industrial Field Bus Communications
 - DeviceNet, CAN, RS485
- Programmable Logic Control
- Isolated Data Acquisition System
- Voltage Level Translator



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SOP 6 PINS

MARKING DIAGRAM



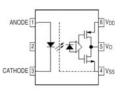
- ON = Corporate Name
- 8173 = Device Number

V

Р

- = DIN EN/IEC60747-5-5 Option
- XX = Two Digit Year Code
- YY = Digit Work Week
 - = Assembly Package Code

PIN CONNECTIONS



TRUTH TABLE

LED	vo
Off	High
On	Low

ORDERING INFORMATION

See detailed ordering and shipping information on page 9 of this data sheet.

SAFETY AND INSULATIONS RATING

As per DIN EN/IEC 60747–5–5, this optocoupler is suitable for "safe electrical insulation" only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Table 1.

Parameter		Charact	teristics
		FOD8173	FOD8173T
	< 150 VRMS	I–IV	I–IV
Installation Classifications per	< 300 VRMS	I–IV	I–IV
DIN VDE 0110/1.89 Table 1, For Rated ains Voltage	< 450 VRMS	I–III	I–IV
	< 600 VRMS	I–III	I–III
Climatic Classification		40/100/21	40/100/21
Pollution Degree (DIN VDE 0110/1.89)		2	2
Comparative Tracking Index		175	175

Table 2.

		Charac		
Symbol	Parameter	FOD8173	FOD8173T	Unit
	Input-to-Output Test Voltage, Method B, VIORM x 1.875 = VPR, 100% Production Test with tm = 1 s, Partial Discharge < 5 pC	1,671	2,137	Vpeak
V _{PR}	Input-to-Output Test Voltage, Method A, VIORM x 1.6 = VPR, Type and Sample Test with tm = 10 s, Partial Discharge < 5 pC	1,426	1,824	Vpeak
V _{IOR} M	Maximum Working Insulation Voltage	891	1,140	Vpeak
V _{IOT} M	Highest Allowable Over-Voltage	6,000	8,000	Vpeak
	External Creepage	≥ 8.0	≥ 8.0	mm
	External Clearance	≥ 7.0	≥ 8.0	mm
DTI	Distance Through Insulation (Insulation Thickness)	≥ 0.4	≥ 0.4	mm
T _S I _{S,INPUT} PS,OUTPUT	Safety Limit Values – Maximum Values Allowed in the Event of a Failure, Case Temperature Input Current Output Power	150 200 300	150 200 300	°C mA mW
R _{IO}	Insulation Resistance at T_S , VIO = 500 V	>10 ⁹	>10 ⁹	Ω

Symbol	Parameter	Value	Units
T _{STG}	Storage Temperature	-40 to +125	°C
T _{OPR}	Operating Temperature	-40 to +100	°C
TJ	Junction Temperature	-40 to +125	°C
T _{SOL}	Lead Solder Temperature (Refer to Reflow Temperature Profile)	260 for 10sec	°C
Input Characteristics			
١ _F	Average Forward Input Current	20	mA
V _R	Reverse Input Voltage	5.0	V
P _{DI}	Input Power Dissipation (Note 1)	40	mW
Output Characteristics			
V _{DD}	Supply Voltage	0 to 6.0	V
Vo	Output Voltage	-0.5 to VDD + 0.5	V
Ι _Ο	Average Output Current	10	mA
P _{DO}	Output Power Dissipation (Note 1)	70	mW

Table 3. ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise specified)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. ON Semiconductor does not recommend exceeding them or designing to Absolute Maximum Ratings.

Table 4.

Symbol	Parameter	Min.	Max.	Unit
T _A	Ambient Operating Temperature	-40	+100	°C
V _{DD}	Supply Voltages (Note 2)	3.0	5.5	V
V _{FL}	Logic Low Input Voltage	0	0.8	V
I _{OL}	Logic Low Output Current	0	7	mA
I _{FH}	Logic High Input Current	5.0	16	mA

Table 5. ISOLATION CHARACTERISTICS

(Apply over all recommended conditions, typical value is measured at TA = 25°C)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
V _{ISO}	Input–Output Isolation Voltage	$\begin{array}{l} TA = 25^{\circ}C, \ R.H. < 50\%, \ t = 1.0min, \\ II-O \ \leq \ 20\mu A \\ (Notes \ 3, \ 4) \end{array}$	5,000			V _{ACRMS}
R _{ISO}	Isolation Resistance	VI-O = 500V (Note 3)		10 ¹¹		Ω
C _{ISO}	Isolation Capacitance	VI–O = 0V, freq=1.0Mhz (Note 3)		1.0		pF

1. No derating required to 100°C.

2. 0.1 µF bypass capacitor must be connected between 4 and 6.

3. Device is considered a two terminal device: Pins 1, 2 and 3 are shorted together and Pins 4, 5, and 6 are shorted together.

4. 5,000 VAC_{RMS} for 1 minute duration is equivalent to 6,000 VAC_{RMS} for 1 second duration.

Table 6. ELECTRICAL CHARACTERISTICS

(Apply over all recommended conditions, $T_A = -40^{\circ}C$ to $+100^{\circ}C$, $3.0V \le V_{DD} \le 5.5V$, unless otherwise specified. Typical value is measured at $T_A = 25^{\circ}C$ and $V_{DD} = 3.3V$.)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
INPUT CHA	RACTERISTICS				•	•
V _F	Forward Voltage	I _F = 10 mA	1.0	1.35	1.80	V
BV _R	Input Reverse Breakdown Voltage	I _R = 10 μA	5.0	18		V
I _{FHL}	Threshold Input Current			2.8	5.0	mA
OUTPUT CH	IARACTERISTICS	· ·	•			•
		I _O = 20 uA, I _F = 10 mA		0.0027	0.01	
V _{OL} Logic Low Output Voltage	I _O = 4 mA, I _F = 10 mA		0.27	0.8	V	
	$V_{DD} = 3.3 \text{ V}, \text{ I}_{O} = -20 \ \mu\text{A}, \text{ I}_{F} = 0 \ \text{mA}$	V _{DD} – 0.1	3.3			
		$V_{DD} = 3.3 \text{ V}, I_O = -4 \text{ mA}, I_F = 0 \text{ mA}$	V _{DD} – 0.5	3.1		
V _{OH}	Logic High Output Voltage	V_{DD} = 5.0 V, I _O =-20 µA, I _F = 0 mA	V _{DD} – 0.1	5.0		V
		$V_{DD} = 5.0 \text{ V}, \text{ I}_{O} = -4 \text{ mA}, \text{ I}_{F} = 0 \text{ mA}$	V _{DD} – 0.5	4.9		
	Logic Low Output Supply	I _F = 10 mA, V _{DD} = 3.3 V		3.3	4.8	
IDDL	Current	I _F = 10 mA, V _{DD} = 5.0 V		4.0	5.0	
	Logic High Output Supply	I _F = 0 mA, V _{DD} = 3.3 V		3.3	4.8	mA
IDDH	Current	$l = -0 m \Lambda / l = -5 0 / l$		4.0	5.0	1

Table 7. SWITCHING CHARACTERISTICS

Apply over all recommended conditions, ($T_A = -40^{\circ}C$ to $+100^{\circ}C$, $3.0V \le V_{DD} \le 5.5V$, $I_F = 5$ mA), unless otherwise specified. Typical value is measured at $T_A = 25^{\circ}C$ and $V_{DD} = 3.3V$.

 $I_F = 0 \text{ mA}, V_{DD} = 5.0 \text{ V}$

4.0

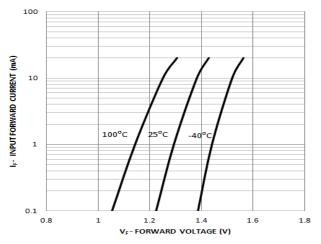
5.0

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
Date Rate (Note 5)					20	Mbit/sec
t _{PW}	Pulse Width		50			ns
t _{PHL}	Propagation Delay Time to Logic Low Output	C _L = 15pF		25	55	ns
t _{PLH}	Propagation Delay Time to Logic High Output	C _L = 15pF		25	55	ns
PWD	Pulse Width Distortion, t _{PHL} – t _{PLH}	C _L = 15pF		5.5	20	ns
t _R	Output Rise Time (10% – 90%)	C _L = 15pF		7.0		ns
t _F	Output Fall Time (90% – 10%)	C _L = 15pF		7.0		ns
CM _H	Common Mode Transient Immunity at Output High	$I_F = 0mA, V_O > 0.8V_{DD},$ $V_{CM} = 1000V, T_A = 25^{\circ}C$ (Note 6)	20	40		kV/μs
CM _L	Common Mode Transient Immunity at Output Low	I _F = 5mA, V _O < 0.8V, V _{CM} = 1000V, T _A = 25°C (Note 6)	20	40		kV/μs

5. Data rate is based on 10 MHz, 50% NRZ pattern with a 50 nsec minimum bit time.

6. Common mode transient immunity at output high is the maximum tolerable positive dVcm/dt on the leading edge of the common mode impulse signal, Vcm, to assure that the output will remain high. Common mode transient immunity at output low is the maximum tolerable negative dVcm/dt on the trailing edge of the common pulse signal, Vcm, to assure that the output will remain low.

TYPICAL CHARACTERISTICS



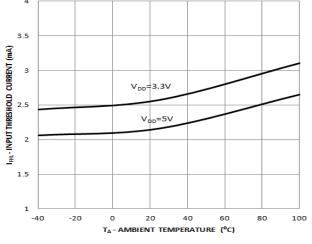


Figure 1. Input Forward Current vs. Forward Voltage

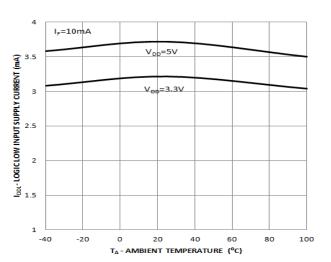


Figure 3. Logic Low Input Supply Current vs. Ambient Temperature

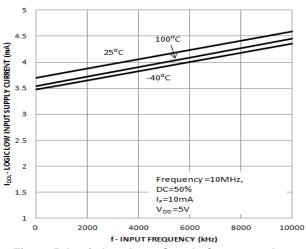


Figure 5. Logic Low Input Supply Current vs. Input Frequency ($V_{DD} = 5 V$)

Figure 2. Input Threshold Current vs. Ambient Temperature

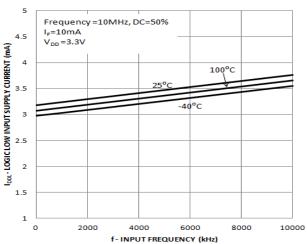
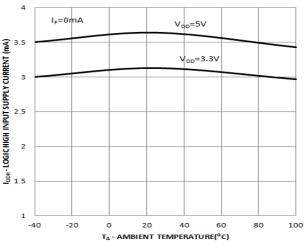
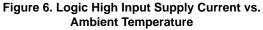
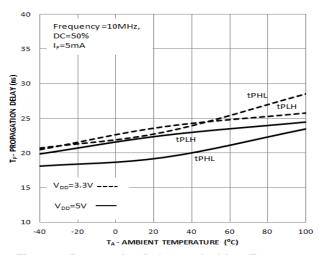


Figure 4. Logic Low Input Supply Current vs. Input Frequency (V_{DD} = 3.3 V)







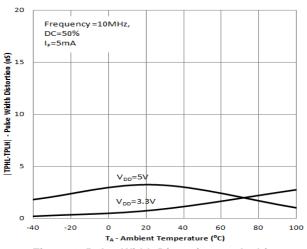


Figure 7. Propagation Delay vs. Ambient Temperature



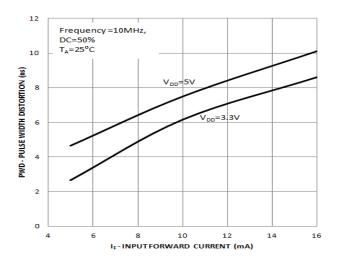


Figure 9. Pulse Width Distortion vs. Input Forward Current

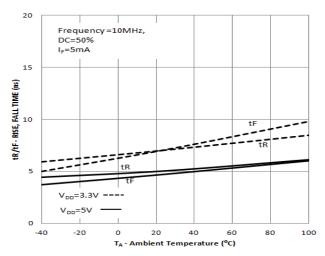


Figure 11. Rise, Fall Time vs. Ambient Temperature

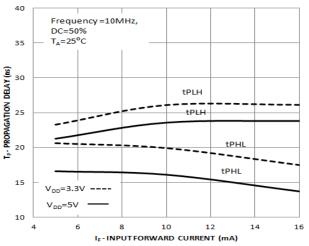
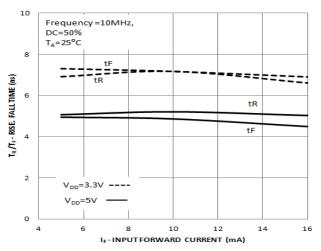
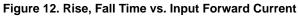


Figure 10. Propagation Delay vs. Input Forward Current





SCHEMATICS

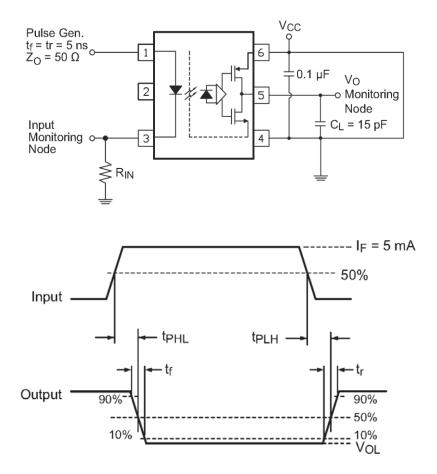


Figure 13. Test Circuit for Propagation Delay Time, Rise Time and Fall Time

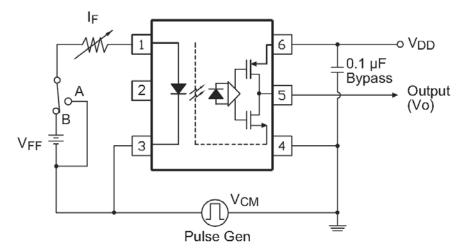


Figure 14. Test Circuit for Instantaneous Common Mode Rejection Voltage

REFLOW PROFILE

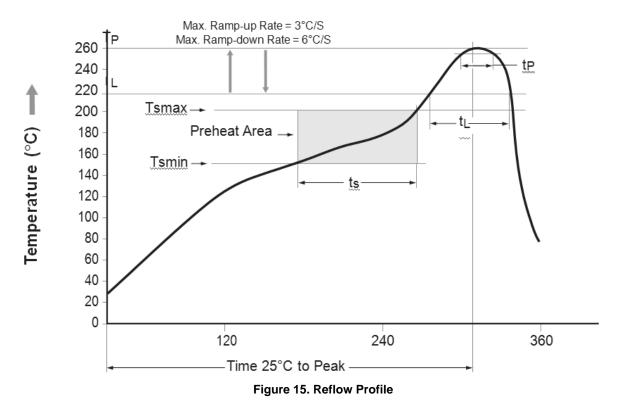
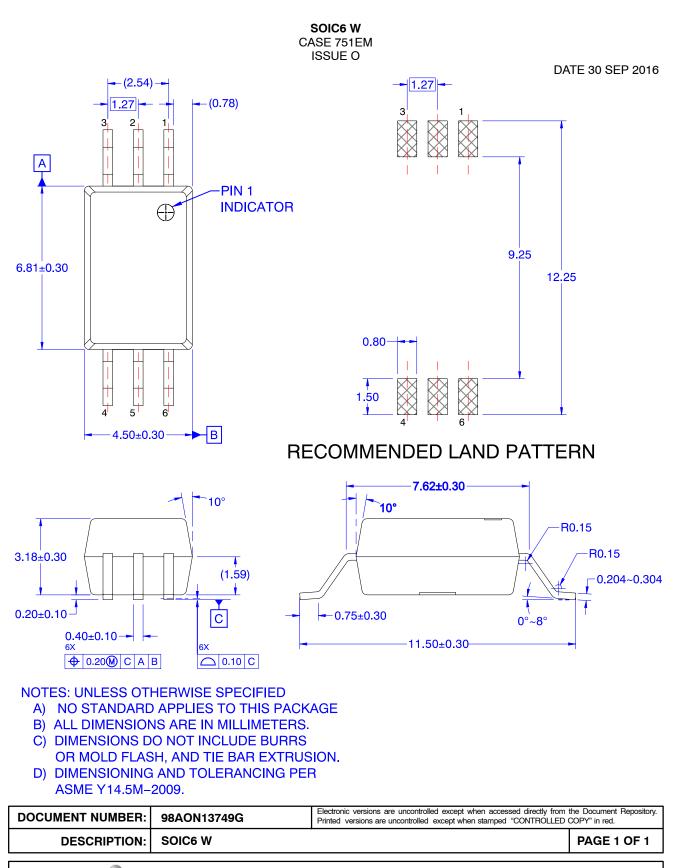


Table 8. REFLOW PROFILE

Profile Feature	Pb–Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (tS) from (Tsmin to Tsmax)	60 – 120 seconds
Ramp-up Rate (tL to tP)	3°C/second max
Liquidous Temperature (TL)	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds
Peak Body Package Temperature	260°C + 0°C / –5°C
Time (tP) within 5°C of 260°C	30 seconds
Ramp-down Rate (TP to TL)	6°C / second max.
Time 25°C to Peak Temperature	8 minutes max.

Table 9. ORDERING INFORMATION

Part Number	Package	Packing Method
FOD8173	Stretched Body SOP 6-Pin	Tube (100 units per tube)
FOD8173R2	Stretched Body SOP 6-Pin	Tape and Reel (1,000 units per reel)
FOD8173V	Stretched Body SOP 6–Pin, DIN EN/IEC60747–5–5 Option (pending)	Tube (100 units per tube)
FOD8173R2V	Stretched Body SOP 6–Pin, DIN EN/ IEC60747–5–5 Option (pending)	Tape and Reel (1,000 units per reel)
FOD8173T	Stretched Body SOP 6-Pin, Wide Lead	Tube (100 units per tube)
FOD8173TR2	Stretched Body SOP 6-Pin, Wide Lead	Tape and Reel (1,000 units per reel)
FOD8173TV	Stretched Body SOP 6–Pin, Wide Lead, DIN EN/IEC60747–5–5 Option (pending)	Tube (100 units per tube)
FOD8173TR2V	Stretched Body SOP 6–Pin, Wide Lead, DIN EN/ IEC60747–5–5 Option (pending)	Tape and Reel (1,000 units per reel)



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